

ABSTRACT OF THE DISCLOSURE

Form a trench in a major surface of a semicon-  
ductor substrate, then bury a paste in the trench.

5 The paste contains solids having a conductive substance  
and a resin, and solvent for dissolving the resin. The  
solids content of the paste is not less than 60 vol%  
and a viscosity ratio thereof is not more than 2.